



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



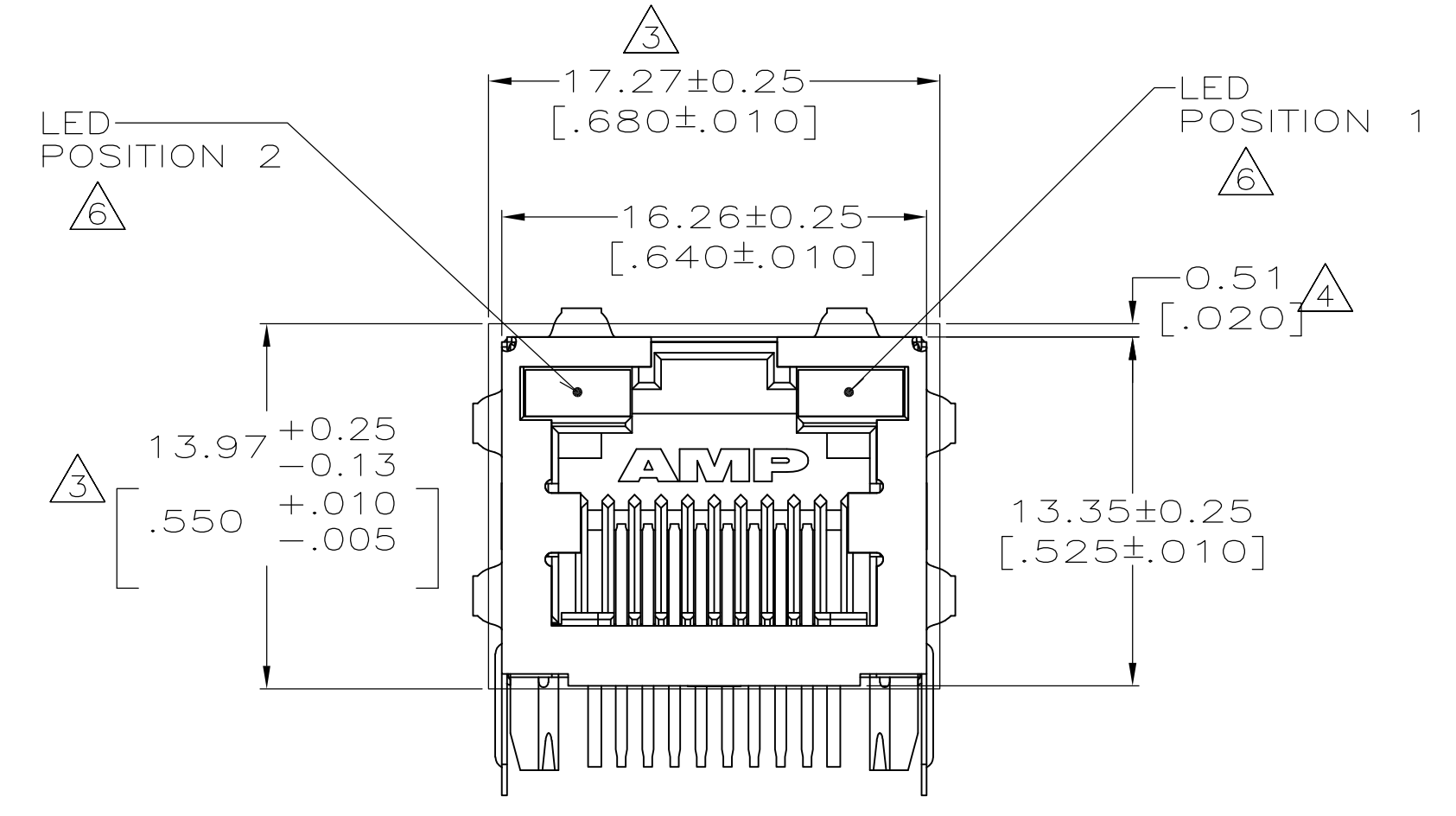
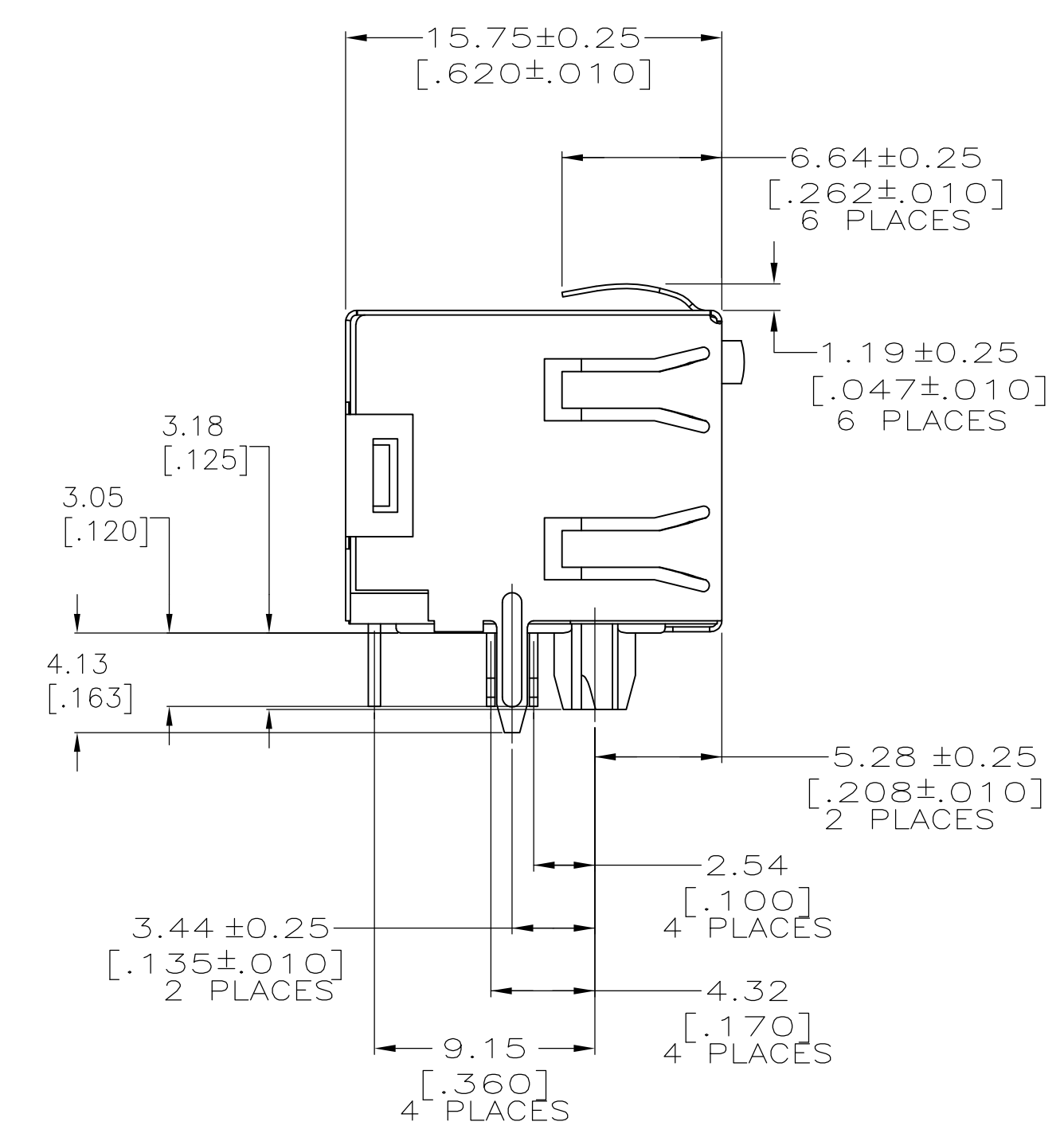
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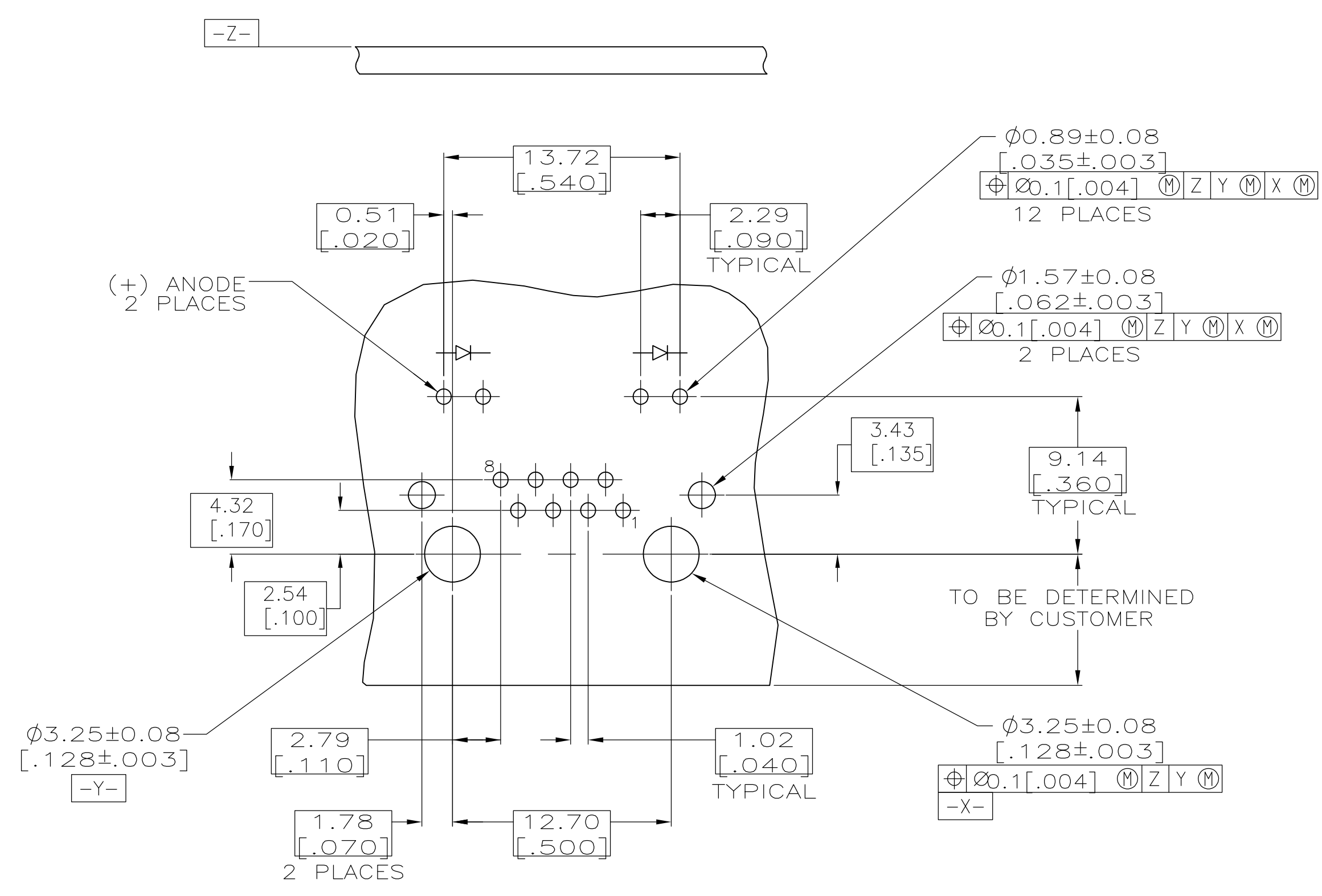
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- MATERIAL:
 HOUSING - HIGH TEMPERATURE THERMOPLASTIC, BLACK, UL94V-0.
 TERMINALS - 0.36[.014] THICK PHOS BRONZE PLATED WITH 3.81µm[.000150] MINIMUM THICK BRIGHT TIN LEAD IN SOLDER AREA. 1.27µm[.000050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27µm[.000050] MINIMUM THICK NICKEL.
 SHIELD - 0.196[.0077] THICK COPPER ZINC ALLOY PREPLATED WITH 1.27µm[.000050] MINIMUM SATIN NICKEL WITH 2.03µm[.000080] MINIMUM TIN POST DIPPED ON PCB GROUND TABS.
 LIGHT EMITTING DIODE (LED) - DIFFUSED EPOXY LENS, 0.51 x 0.51[.020 x .020] CARBON STEEL (WIREFRAME LEADS) PREPLATED WITH 8.89µm[.000350] THICK TIN/COPPER OVER 2.03µm[.000080] THICK SILVER OVER 1.02µm[.000040] THICK COPPER OVER 3.56µm[.000140] THICK NICKEL OVER 1.02µm[.000040] THICK COPPER UNDERPLATE
- JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- △ SUGGESTED PANEL OPENING DIMENSIONS.
- △ SUGGESTED CLEARANCE BETWEEN TOP OF CONNECTOR AND TOP PANEL OPENING.
- 0.051[.002] WHITE POLYESTER INSULATOR APPLIED TO BACK OF HOUSING.
- △ SEE TABLE FOR COLOR OF LEDS AND NUMBER REQUIRED.
- THIS MODULAR JACK WITH INTEGRATED LED IS NOT IR REFLOW SOLDERING PROCESS COMPATIBLE.



GREEN	GREEN	1116173-5
GREEN	YELLOW	1116173-4
YELLOW	GREEN	1116173-1
POSITION 2	POSITION 1	PART NUMBER

SUGGESTED PRINTED CIRCUIT BOARD LAYOUT
(COMPONENT SIDE)

THIS DRAWING IS A CONTROLLED DOCUMENT.		DIN D. STRAUSSER 25MAR98	Tyco Electronics Corporation Harrisburg, PA 17105-3608	
DIMENSIONS: mm [INCHES]		CHK F. LAURER 27MAR98	Tyco Electronics	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD F. LAURER 27MAR98	NAME	
0. PLC ± -		PRODUCT SPEC		
1. PLC ± -		108-1163-4		
2. PLC ± 0.25[.01]		APPLICATION SPEC		
3. PLC ± 0.13[.005]		114-2154		
4. PLC ± -		WEIGHT		
ANGLES ± -		A1 00779 ©=1116173		
MATERIAL SEE NOTE 1	FINISH SEE NOTE 1	RESTRICTED TO	CUSTOMER DRAWING	
		SCALE 4:1	SHEET 1 of 1	REV E